

January 2005 Revised February 2005

FSUSB22

Low Voltage Ultra Low Power USB High Speed (480 Mbps) Dual DPDT Switch

General Description

FSUSB22 is a low power high bandwidth analog switch specially designed for applications of the switching of high speed USB 2.0 signals in handset and consumer applications such as cell phone, digital camera, and notebook with hubs or controllers of limited USB I/O. The wide bandwidth (750MHz) of this switch allows signals to pass with minimum edge and phase distortion. Superior channel-to-channel crosstalk results in minimal interference. It is compatible with high speed USB2.0 standard.

Features

- -40dB OFF Isolation at 250MHz
- -40dB non-adjacent channel crosstalk at 250MHz
- 4.5Ω typical On Resistance (R_{ON})
- -3dB bandwidth: 750MHz
- Low power consumption (1uA max)
- Control input: TTL compatible
- Bidirectional operation
- USB high speed and full speed signaling capability

Applications

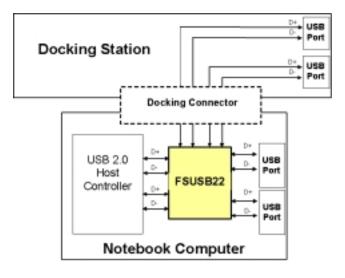
• Cell phone, PDA, digital camera, and notebook

Ordering Code:

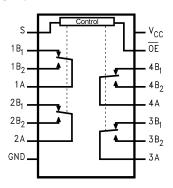
Order Number	Package Number	Package Description
FSUSB22BQX	J	Pb-Free 16-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.5mm
FSUSB22QSC (Preliminary)	MQA16	16-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150" Wide
FSUSB22MTC (Preliminary)	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code

Pb-Free package per JEDEC J-STD-020B.



Analog Symbol



Pin Descriptions

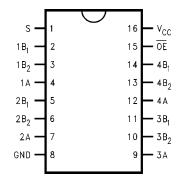
Pin Name	Description				
ŌE	Bus Switch Enable				
S	Select Input				
A	Bus A				
B ₁ -B ₂	Bus B				

Truth Table

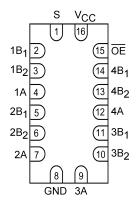
s	OE	Function
Х	Н	Disconnect
L	L	A = B ₁
Н	L	A = B ₂

Connection Diagrams

Pin Assignments for QSOP and TSSOP (Preliminary)



Pad Assignments for DQFN



Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC}) $$-0.5\mbox{V}$ to +4.6\mbox{V}$ DC Switch Voltage (V_S) $-0.5\mbox{V}$ to V_{CC} +0.05\mbox{V}$ }$

DC Input Voltage (V_{IN}) (Note 2) -0.5V to +4.6V DC Input Diode Current (I_{IK}) V_{IN} < 0V -50 mA

DC Output (I_{OUT}) Sink Current 128 mA

DC V_{CC}/GND Current (I_{CC}/I_{GND}) ± 100 mA Storage Temperature Range (T_{STG}) -65° C to +150 °C

ESD

Human Body Model

Recommended Operating Conditions (Note 3)

Power Supply Operating (V_{CC}) 3.0V to 3.6V Input Voltage (V_{IN}) 0V to V_{CC}

Output Voltage (V_{IN})

Over the V_{CC}

Over the V_{CC}

Over the V_{CC}

Input Rise and Fall Time (t_r, t_f)

Switch Control Input 0 ns/V to 5 ns/V
Switch I/O 0 ns/V to DC

Free Air Operating Temperature (T_A) $-40~^{\circ}C$ to $+85~^{\circ}C$

Note 1: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum rating. The Recommended Operating Conditions tables will define the conditions for actual device operation.

Note 2: The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Note 3: Unused control inputs must be held HIGH or LOW. They may not float

DC Electrical Characteristics

	Parameter	V _{CC} (V)	T _A =	-40 °C to +	85 °C	Units	Conditions
Symbol			Min	Typ (Note 4)	Max		
V _{IK}	Clamp Diode Voltage	3.0			-1.2	V	$I_{IN} = -18 \text{ mA}$
V _{IH}	HIGH Level Input Voltage	3.0 - 3.6	2.0			V	
V _{IL}	LOW Level Input Voltage	3.0 - 3.6			0.8	V	
I _I	Input Leakage Current	3.6			±1.0	μΑ	$0 \le V_{IN} \le 3.6V$
I _{OFF}	OFF-STATE Leakage Current	3.6			±1.0	μΑ	$0 \le A, B \le V_{CC}$
R _{ON}	Switch On Resistance (Note 5)	3.0		5.0	7.0	Ω	$V_{IN} = 0.8V$ $I_{ON} = 8 \text{ mA}$
		3.0		4.5	6.5	Ω	V _{IN} = 3.0V I _{ON} = 8 mA
ΔR_{ON}	Delta R _{ON}	3.0		0.3		Ω	$V_{IN} = 0.8V$, $V_{IN} = 0V - 1.5V$, $I_{ON} = 8 \text{ mA}$
R _{FLAT(ON)}	On Resistance Flatness (Note 6)	3.0		1.0	1.3	Ω	I _{OUT} = 8 mA
I _{CC}	Quiescent Supply Current	3.6			1.0	μΑ	V _{IN} = V _{CC} or GND, I _{OUT} = 0

Note 4: Typical values are at V_{CC} = 3.0V and T_A = +25°C

Note 5: Measured by the voltage drop between A and B pins at the indicated current through the switch. On Resistance is determined by the lower of the voltages on the two (A or B) pins.

Note 6: Flatness is defined as the difference between the maximum and minimum value On Resistance over the specified range of conditions.

AC Electrical Characteristics

	Parameter	V _{CC} (V)	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$					Figure
Symbol			Min	Typ (Note 7)	Max	Units	Conditions	Number
t _{ON}	Turn ON Time S-to-Bus B	3.0 to 3.6		4.5	6.0	ns		Figures 5, 6
t _{OFF}	Turn OFF Time S-to-Bus B	3.0 to 3.6		2.5	4.0	ns		Figures 5, 6
t _{PD}	Propagation Delay	3.0 to 3.6		0.25		ns	C _L = 10 pF	Figure 10
O _{IRR}	Non-Adjacent OFF-Isolation	3.0 to 3.6		-55.0		dB	$f = 10MHz, R_L = 50\Omega$	Figure 7
X _{TALK}	Non-Adjacent Channel Crosstalk	3.0 to 3.6		-75.0		dB	$R_L = 50\Omega$, $f = 10MHz$	Figure 8
BW	-3dB Bandwidth	3.0 to 3.6		750		MHz	$R_L = 50\Omega$	Figure 9

Note 7: Typical values are at $V_{CC} = 3.3V$ and $T_A = +25$ °C

USB Related AC Electrical Characteristics (Note 8)

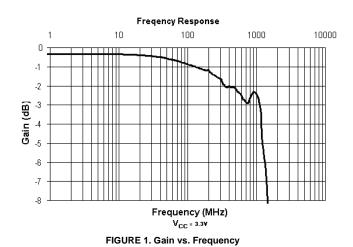
Symbol	Parameter	V _{CC}	$T_A = -40$ °C to $+85$ °C		Units	Conditions	Figure	
Cyllibol		(V)	Min	Тур	Max	Oille		Number
t _{SK(O)}	Channel-to-Channel Skew	3.0 to 3.6		0.051		ns	C _L = 10 pF	Figures 10, 11
t _{SK(P)}	Skew of Opposite Transition of the Same Output	3.0 to 3.6		0.020		ns	C _L = 10 pF	Figures 10, 11
TJ	Total Jitter	3.0 to 3.6		0.210			$R_L = 50\Omega$, $C_L = 10 \text{ pF}$ $t_R = t_F = 750 \text{ps}$ at 480 Mbps	

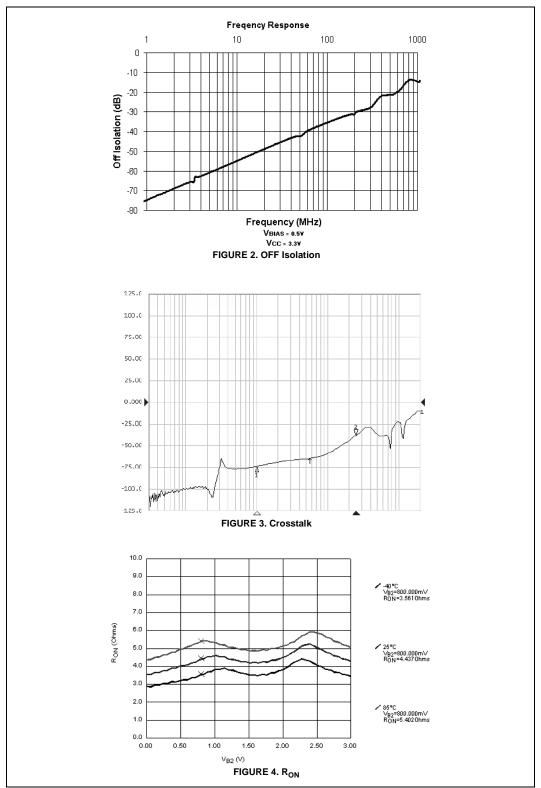
Note 8: Typical values are at V_{CC} = 3.3V and T_A = +25°C

Capacitance (Note 9)

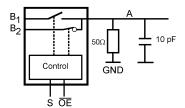
Symbol	Parameter	T _A = -40°C to +85°C		Conditions
		Тур		
C _{IN}	Control Pin Input Capacitance	2.5	pF	V _{CC} = 0V
C _{ON}	A/B ON Capacitance	12.0	pF	$V_{CC} = 3.3V, \overline{OE} = 0V$
C _{OFF}	Port B OFF Capacitance	4.5	pF	V_{CC} and $\overline{OE} = 3.3V$

Note 9: Typical values are at $V_{CC} = 3.3V$ and $T_A = +25^{\circ}C$





AC Loading and Waveforms



Note: Input driven by 50Ω source terminated in 50Ω Note: C_L includes load and stray capacitance

Note: Input PRR = 1.0 MHz, t_W = 500 ns

FIGURE 5. AC Test Circuit

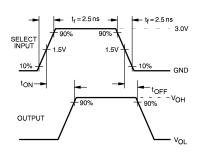


FIGURE 6. AC Waveforms

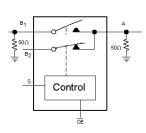


FIGURE 7. OFF Isolation Test

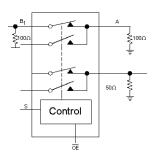


FIGURE 8. Crosstalk Test

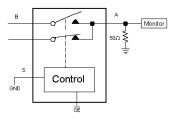
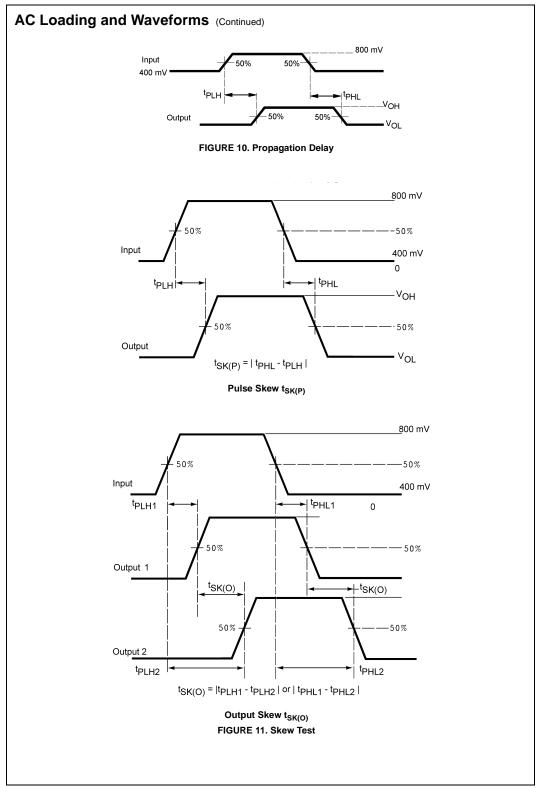
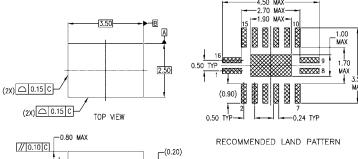


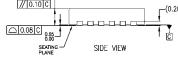
FIGURE 9. Bandwidth Test

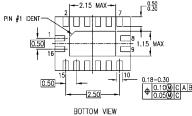


Tape and Reel Specification Tape Format for DQFN Cover Tape Package Number Tape Cavity Designator Section Cavities Status Status Leader (Start End) 125 (typ) **Empty** Sealed BQX 2500/3000 Filled Sealed Carrier Trailer (Hub End) 75 (typ) **Empty** Sealed TAPE DIMENSIONS inches (millimeters) D, User Direction of Feed Dimensions are in millimeters Kp 4-0: 1.0 Package о, 2.30 2.30 F0.05 /4ilas 2.0 +/-0.005 0.07 175 刊 1.0 2×2 5.5 5.5 2.80 1.5 1.5 1.5 2.0 9.3 9.3 9.3 12 12 12 12 12 12 12 12 16 2.5x3.0 2.50 1.55 1.75 0.3 0.9 0.07 2.5x3.5 2.80 3.80 1.55 1.75 0.9 2.0 0.3 0.07 1.5 1.5 1.5 1.5 5.5 5.5 5.5 5.5 2.5x4.5 3.5x4.5 4.80 4.80 1.75 0.9 2.0 2.0 0.3 9.3 9.3 2.80 1.55 0.07 3.80 1.55 0.07 2.5x3.0 2.50 4.35 3.30 4.35 1.55 1.75 0.9 2.0 0.3 0.07 93 4×4 2.0 9.3 13.3 5.35 5.35 6.30 6.30 1.55 0.3 6 x 6 1.5 1.75 Notes: Ao. Bo, and Ko dimensions are determined with respect to the EIA Jiedec RS-481 rotational and lateral movement requirements (see sketches A. B. and C). 1.0 mm 10º maximum maximum - + +; Typical component cavity center line 1.0 mm Typical component maximu 10 deg maximum component rotation Sketch A (Side or Front Sectional View) Sketch C (Top View) Component Rotation Sketch B (Top View) Component Rotation Shipping Reel Dimension W1 Measured at Hub W2 max Measured at Hub Dia D Dia A DETAIL AA See detail AA ₩3 Dimensions are in millimeters Dia C +.54.2 Tape Width Dia A Dim B Dia D Die N Dim W1 Dim W2 max min +240 max (LSL - USL) 330 1.5 13 20.2 178 6.4 14.4 7.9~10.4 12 330 1.5 13 20.2 178 12.4 18.4 11.9-15.4 16 330 15.9-19.4 1.5 13 20.2 178 19.4 22.4

Physical Dimensions inches (millimeters) unless otherwise noted





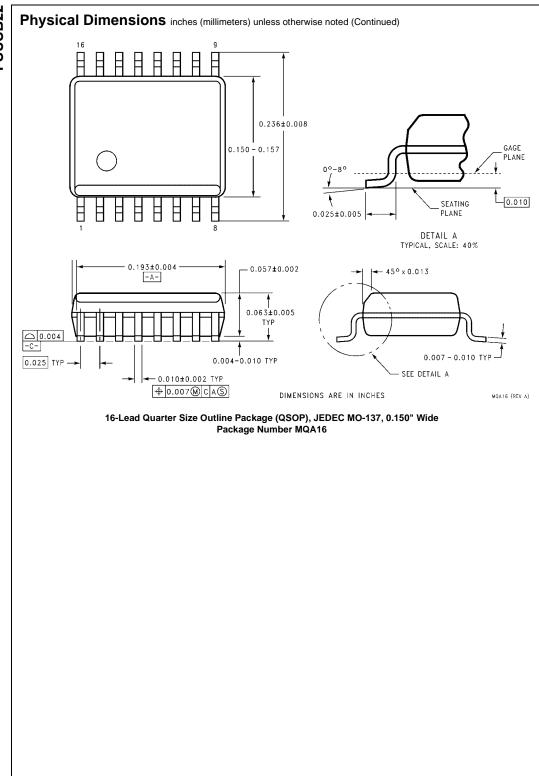


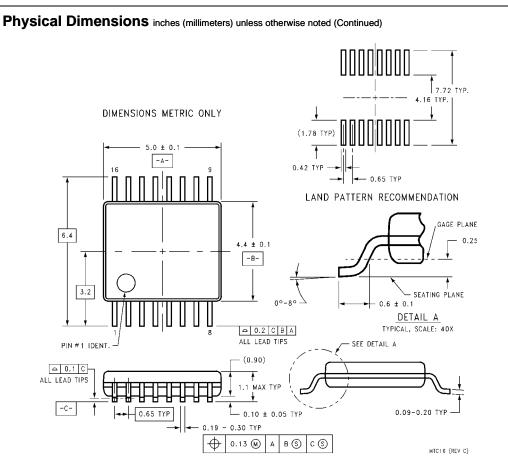
NOTES:

- A. CONFORMS TO JEDEC REGISTRATION M0-241, VARIATION AB
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP016ErevA

Pb-Free 16-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.5mm Package Number MLP016E





16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC16

Technology Description

The Fairchild Switch family derives from and embodies Fairchild's proven switch technology used for several years in its 74LVX3L384 (FST3384) bus switch product.

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